



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sarah E. Kim et al. Art Unit: 2814  
Serial No.: 10/659,044 Examiner: Not yet assigned  
Filed : September 9, 2003 Assignee: Intel Corporation  
Title : THICK METAL LAYER INTEGRATED PROCESS FLOW TO IMPROVE  
POWER DELIVERY AND MECHANICAL BUFFERING

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

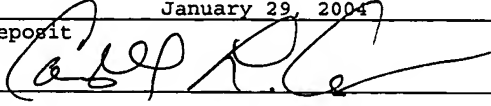
Prior to examination, please amend the application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 29, 2004  
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